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Part Number: **0736590004**
Status: **Active**
Overview: HDM® Backplane Connector System
Description: HDM Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 12 Circuits, Gold (Au) 0.76µm

Documents:

[3D Model](#) [Packaging Specification PK-70873-0819 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

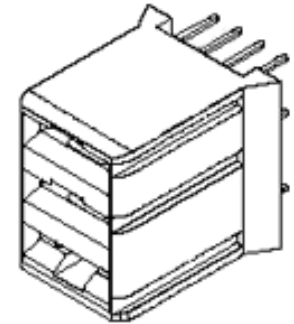
CSA LR19980
 UL E29179

General

Product Family Backplane Connectors
 Series 73659
 Application Backplane
 Comments Midplane Power Module
 Component Type Power Header
 Overview HDM® Backplane Connector System
 Product Name HDM
 UPC 800755024852

Physical

Circuits (Loaded) 12
 Circuits (maximum) 12
 Color - Resin Black
 Durability (mating cycles max) 250
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part No
 Keying to Mating Part None
 Material - Metal Beryllium Copper
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 Net Weight 1.609/g
 Number of Columns 1
 Number of Pairs Open Pin Field
 Number of Rows 3
 Orientation Vertical
 PC Tail Length 3.50mm
 PCB Locator No
 PCB Retention Yes
 PCB Thickness - Recommended 2.50mm
 Packaging Type Tube
 Pitch - Mating Interface 2.00mm
 Pitch - Termination Interface 2.00mm
 Plating min - Mating 0.762µm
 Plating min - Termination 3.810µm
 Polarized to PCB No
 Stackable Yes
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -55°C to +105°C
 Termination Interface: Style Through Hole



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Not Contained Per -
 ED/30/2017 (7 July
 2017)

Halogen-Free

Status

Low-Halogen

**Need more information on product
 environmental compliance?**

Email productcompliance@molex.com
 Please visit the [Contact Us](#) section for any
 non-product compliance questions.

China ROHS

ELV

RoHS Phthalates

Green Image

Not Relevant

Not Contained

Search Parts in this Series

73659 Series

Mates With

73651 HDM Board-to-Board Daughterboard
 Power Module

Electrical

Current - Maximum per Contact	15.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	38
Shielded	Yes
Voltage - Maximum	500V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	REFLOW
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260

Material Info**Reference - Drawing Numbers**

Packaging Specification	PK-70873-0819
Sales Drawing	SDA-73659-000*

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